

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of the claims in this application.

LISTING OF CLAIMS:

1. (Currently Amended) Apparatus for ~~supporting~~ supporting, during a testing operation operation, a leadframe formed with at least one row of non-singulated semiconductor devices, comprising a main body and a leadframe support member, wherein said leadframe support member is formed with at least one groove for receiving said semiconductor devices such ~~that in-use~~ that, during the testing operation, leads extending from said devices ~~lie on~~ rest upon a surface of said support member.

2. (Original) Apparatus as claimed in claim 1 wherein said leadframe support member is formed with a plurality of parallel grooves.

3. (Original) Apparatus as claimed in claim 1 further comprising means for releasably gripping a said leadframe so as to hold said leadframe in place.

4. (Original) Apparatus as claimed in claim 3 wherein said gripping means comprises a pair of gripping members disposed on respective sides of said groove.

5. (Previously Presented) Apparatus as claimed in claim 4 wherein means are provided for moving said gripping members into and out of engagement with said leadframe.

6. (Previously Presented) Apparatus as claimed in claim 5 wherein said moving means is actuated by compressed air.

7. (Original) Apparatus as claimed in claim 6 wherein a plurality of pairs of gripping members are provided, and wherein said compressed air is provided directly to one said pair and is distributed to the other said pairs by an air distribution assembly formed in the main body.

8. (Original) Apparatus as claimed in claim 3 wherein said gripping means extends through apertures formed in said leadframe support member.

9. (Original) Apparatus as claimed in claim 1 wherein said main body is formed with locating pins for locating the leadframe support member on the main body.

10. (Previously Presented) Apparatus as claimed in claim 1 wherein said main body is formed of a conducting material and an electrical grounding is provided at holes located on the main body.

11. (Original) Apparatus as claimed in claim 1 wherein the leadframe support member is formed of a high resistivity electrically insulating material.

12. (Original) Apparatus as claimed in claim 1 wherein said main body is provided with identification means.

13. (Currently Amended) Apparatus ~~as claimed in claim 1 wherein said main body is formed with~~ for supporting during a testing operation a leadframe formed with at least one row of non-singulated semiconductor devices, comprising a main body, a leadframe support member, wherein said leadframe support member is formed with at least one groove for receiving said semiconductor devices such that in use leads extending from said devices lie on a surface of said support member, and means for coupling said main body with a transport mechanism.

14. (New) Apparatus as claimed in claim 1, wherein each groove receives a plurality of semiconductor devices.

15. (New) Apparatus as claimed in claim 2, wherein each groove receives a plurality of semiconductor devices.